FORMULATION AND PROCESSING SOLUTION FOR DICING PROCESS

ABSTRACT

A formulation for a wafer dicing process comprises 1.0 to 1.5 mass% of a partially saponified polyvinyl alcohol having a polymerization degree of 200 to 400 and a saponification degree of 75 to 85 mol%; 0.4 to 0.6 mass% of polyoxyethylene- polyoxypropylene glycol ether having a number average molecular weight of 10,000 to 20,000 with a polymerization ratio of polyoxyethylene to polyoxypropylene of 75:25 to 85:15; and pure water (all mass% based on 100 mass% of formulation). The formulation is used in the form of a processing solution obtained by diluting it 10,000 to 100,000 times by pure water and flowing it on a dicing blade in a wafer dicing process to effectively remove dicing offcuts from the wafer and minute pieces of adhesive released from an adhesive layer of a dicing tape.

(No suitable figure)